

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Jan. 09, 2013

Expected First Date Code of Changed Product : 1302

Description of Change (From) :

Current assembly of the MLP 3.3x3.3 8L and MLP 2X2 6L Packages, at Fairchild Semiconductor Penang, Malaysia.

| | |
|---------------|---|
| BOM | Fairchild Penang |
| Wire | 2.0 mil Cu |
| Die Attach | QMI519 |
| Leadframe | C194 /CU194 Cu with full NiPdAu plating |
| Mold Compound | Hitachi CEL9220HF13FC1 |

Description of Change (To) :

Addition of Hana Semiconductor AYT, Thailand as alternate manufacturing site for MLP 3.3x3.3 8L and MLP 2X2 6L Packages.

There is no changes to current package specifications and dimension drawings.

| BOM | Fairchild Penang | HANA Semiconductor Ayutthaya |
|---------------|---|---|
| Wire | 2.0 mil Cu | 2.0 mil Cu |
| Die Attach | QMI519 | Ablebond 8600 |
| Leadframe | C194 /CU194 Cu with full NiPdAu plating | Samsung C194 with full NiPdAuAg plating |
| Mold Compound | Hitachi CEL9220HF13FC1 | Hitachi CEL9220HF13H |

Reason for Change:

MLP 3.3x3.3 8L and MLP2X2 6L are qualified packages at alternate assembly and test site Hana AYT (Thailand) under PCN Q1100402 and Q4104305 respectively. It had started mass production since 2010. The plan is to transfer additional devices as listed in this PCN to Hana AYT as alternate site. This product will remain fully compliant to all published specifications.

Affected Product(s):

| | | |
|---------------|---------------|------------|
| FDMA8878 | FDMA8884 | FDMA905P |
| FDMA905P_F130 | FDMA905P_F147 | FDMC86102L |
| FDMC86102LZ | FDMC86240 | FDMC86320 |

| Qualification Plan | Device | Package | Process | No. of Lots |
|--------------------|----------|---------------|---------|-------------|
| Q20100027 | FDMC7664 | MLP3.3X3.3_8L | PT7 N | 1 |

| Test Description: | Condition: | Standard : | Duration: | Results: |
|--------------------------------|--------------------------|------------------|--------------|----------|
| MSL1 Precondition | 260C, 3 cycles | JESD22-A113 | | 0/231 |
| High Temperature Gate Bias | 150C , BIASED V | JESD22-A108 | 1000 hrs | 0/77 |
| High Temperature Reverse Bias | 150C , BIASED V | JESD22-A108 | 1000 hrs | 0/77 |
| High Temperature Storage Life | 150C | JESD22-A103 | 1000 hrs | 0/77 |
| Highly Accelerated Stress Test | 130C, 85%RH,BIASED V | JESD22-A110 | 96 hrs | 0/77 |
| Power Cycle | Delta 100CC, 2 Min cycle | MIL-STD-750-1036 | 10000 Cycles | 0/77 |
| Temperature Cycle | -65C, 150C | JESD22-A104 | 500 Cycles | 0/77 |
| Unbiased HAST | 130C, 85%RH | JESD22-A118 | 96 hrs | 0/77 |

| Qualification Plan | Device | Package | Process | No. of Lots |
|--------------------|-----------|---------------|---------|-------------|
| Q20110471 | FDMC86240 | MLP3.3X3.3_8L | PT5 MV | 1 |

| Test Description: | Condition: | Standard : | Duration: | Results: |
|--------------------------------|----------------------|-------------|------------|----------|
| MSL1 Precondition | 260C, 3 cycles | JESD22-A113 | | 0/158 |
| High Temperature Gate Bias | 150C, 100% VGSV | JESD22-A108 | 1000 hrs | 0/79 |
| High Temperature Reverse Bias | 150C, 80% BV V | JESD22-A108 | 1000 hrs | 0/79 |
| High Temperature Storage Life | 150C | JESD22-A103 | 1000 hrs | 0/79 |
| Highly Accelerated Stress Test | 130C, 85%RH, 80% BVV | JESD22-A110 | 96 hrs | 0/79 |
| Temperature Cycle | -65C, 150C | JESD22-A104 | 500 Cycles | 0/79 |

| Qualification Plan | Device | Package | Process | No. of Lots |
|--------------------|-----------|-----------|---------|-------------|
| Q20100448 | FDMA430NZ | MLP2X2_6L | PT4 N Z | 1 |

| Test Description: | Condition: | Standard : | Duration: | Results: |
|--------------------------------|--------------------------|------------------|--------------|----------|
| MSL1 Precondition | 260C, 3 cycles | JESD22-A113 | | 0/158 |
| High Temperature Gate Bias | 150C , BIASED V | JESD22-A108 | 1000 hrs | 0/79 |
| High Temperature Reverse Bias | 150C , BIASED V | JESD22-A108 | 1000 hrs | 0/79 |
| High Temperature Storage Life | 150C | JESD22-A103 | 1000 hrs | 0/79 |
| Highly Accelerated Stress Test | 130C, 85%RH,BIASED V | JESD22-A110 | 96 hrs | 0/79 |
| Power Cycle | Delta 100CC, 2 Min cycle | MIL-STD-750-1036 | 10000 Cycles | 0/79 |
| Temperature Cycle | -65C, 150C | JESD22-A104 | 500 Cycles | 0/79 |